

MURD320

SWITCHMODE Power Rectifier

DPAK Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 35 Nanosecond Recovery Time
- Low Forward Voltage Drop
- Low Leakage
- Pb-Free Package is Available

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Available in 16 mm Tape and Reel, 2500 Units Per Reel, by Adding a "T4" Suffix to the Part Number

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 200 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 158^\circ\text{C}$) | $I_{F(AV)}$ | 3.0 | A |
| Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, $T_C = 158^\circ\text{C}$) | I_{FRM} | 6.0 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz) | I_{FSM} | 75 | A |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -65 to +175 | °C |

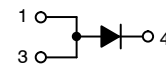
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



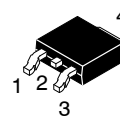
ON Semiconductor®

<http://onsemi.com>

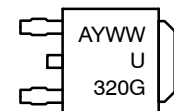
ULTRAFAST RECTIFIER 3.0 AMPERES, 200 VOLTS



MARKING DIAGRAM



DPAK
CASE 369C



A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping† |
|------------|-------------------|------------------|
| MURD320T4 | DPAK | 2500/Tape & Reel |
| MURD320T4G | DPAK (Pb-Free) | 2500/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|---|-----------------|-------|---------------|
| Thermal Resistance – Junction-to-Case | $R_{\theta JC}$ | 6 | $^{\circ}C/W$ |
| Thermal Resistance – Junction-to-Ambient (Note 1) | $R_{\theta JA}$ | 80 | $^{\circ}C/W$ |

ELECTRICAL CHARACTERISTICS

| | | | |
|---|----------|--------------|---------|
| Maximum Instantaneous Forward Voltage Drop (Note 2) ($i_F = 3$ Amps, $T_J = 25^{\circ}C$) ($i_F = 3$ Amps, $T_J = 125^{\circ}C$) | V_F | 0.95 0.75 | Volts |
| Maximum Instantaneous Reverse Current (Note 2) ($T_J = 25^{\circ}C$, Rated dc Voltage) ($T_J = 125^{\circ}C$, Rated dc Voltage) | i_R | 5 500 | μA |
| Maximum Reverse Recovery Time ($I_F = 1$ Amp, $di/dt = 50$ Amps/ μs , $V_R = 30$ V, $T_J = 25^{\circ}C$) ($I_F = 0.5$ Amp, $i_R = 1$ Amp, $I_{REC} = 0.25$ A, $V_R = 30$ V, $T_J = 25^{\circ}C$) | t_{rr} | 35 25 | ns |

- Rating applies when surface mounted on the minimum pad sizes recommended.
- Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

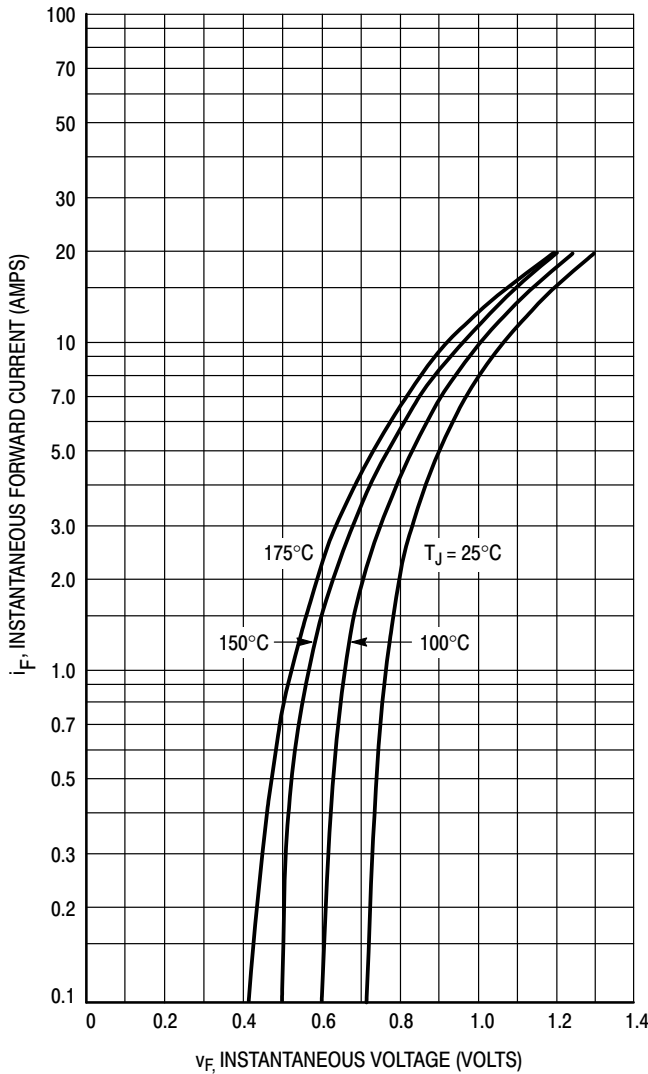


Figure 1. Typical Forward Voltage

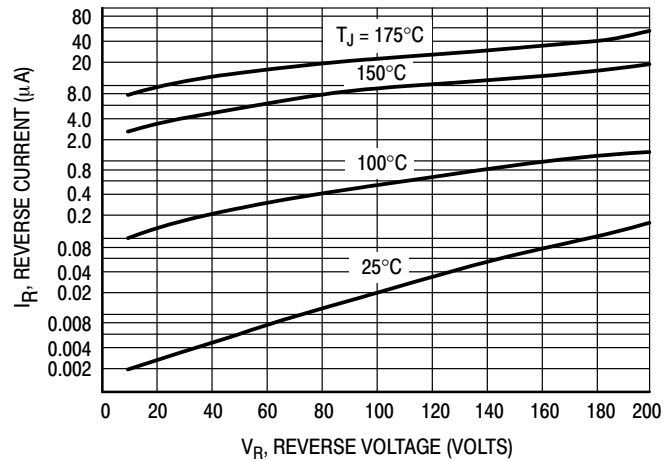


Figure 2. Typical Reverse Current*

* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if V_R is sufficiently below rated V_R .

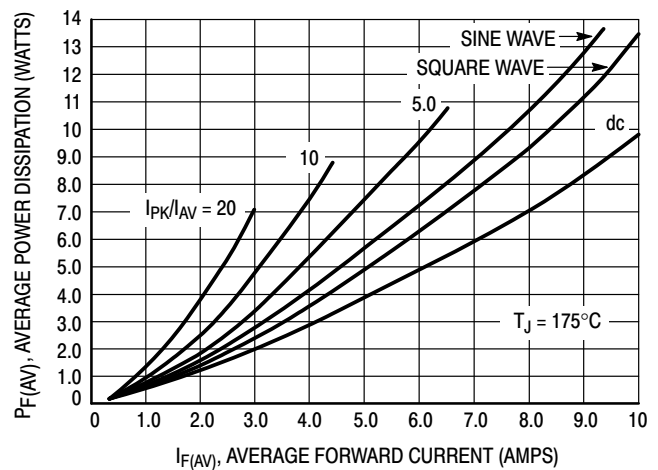


Figure 3. Average Power Dissipation

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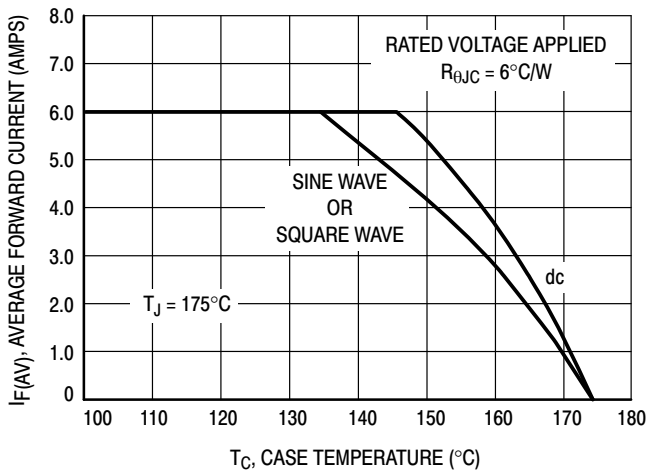


Figure 4. Current Derating, Case

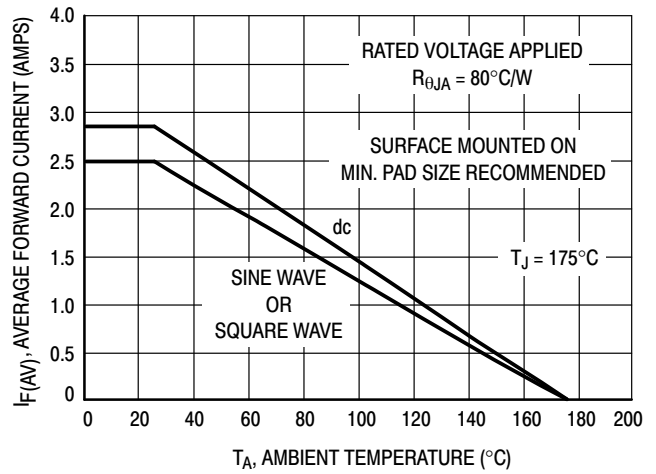


Figure 5. Current Derating, Ambient

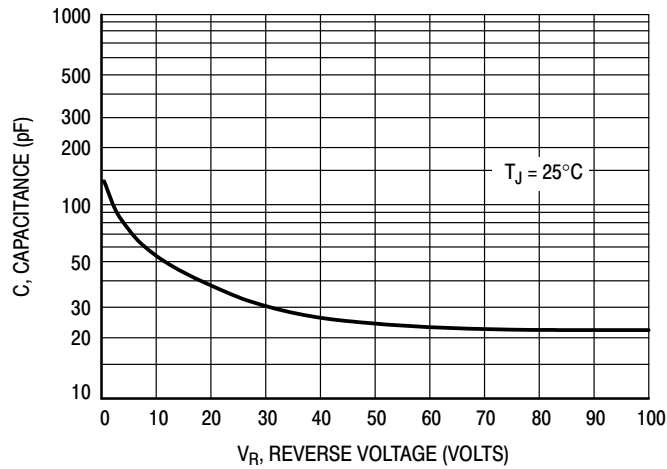
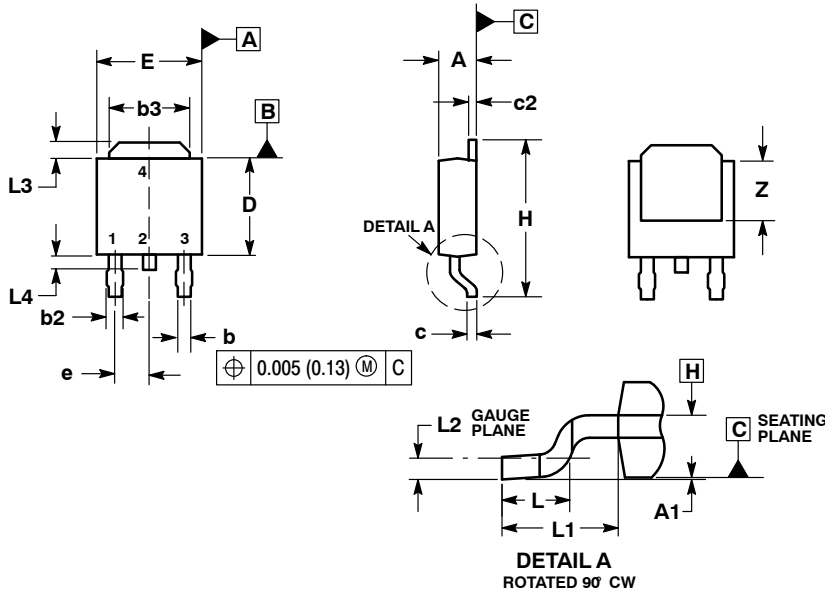


Figure 6. Typical Capacitance

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PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C-01 ISSUE D

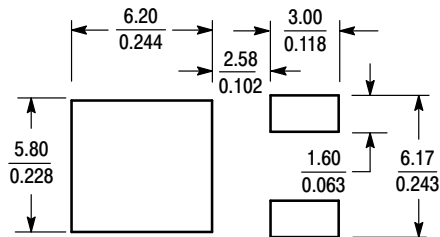


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.086 | 0.094 | 2.18 | 2.38 |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 |
| b | 0.025 | 0.035 | 0.63 | 0.89 |
| b2 | 0.030 | 0.045 | 0.76 | 1.14 |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 |
| D | 0.235 | 0.245 | 5.97 | 6.22 |
| E | 0.250 | 0.265 | 6.35 | 6.73 |
| e | 0.090 BSC | | 2.29 BSC | |
| H | 0.370 | 0.410 | 9.40 | 10.41 |
| L | 0.055 | 0.070 | 1.40 | 1.78 |
| L1 | 0.108 REF | | 2.74 REF | |
| L2 | 0.020 BSC | | 0.51 BSC | |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 |
| L4 | --- | 0.040 | --- | 1.01 |
| Z | 0.155 | --- | 3.93 | --- |

SOLDERING FOOTPRINT*



SCALE 3:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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